

Multilayer Ceramic Capacitor

multicomp PRO

**RoHS
Compliant**



Features:

- For General Purpose
- Capacitor Dielectric Material : Multilayer Ceramic
- Termination : Radial Leaded
- Lead Pitch : 2.54mm

Ordering informations:

MC	0805	B	104	K	500	2.54MM
↓	↓	↓	↓	↓	↓	↓
A	B	C	D	E	F	G

A
Product Type

B	
Unit : Inches	
Chip Size (L×W)	
Code	Chip
0805	0.08 × 0.05
1206	0.12 × 0.06

C	
Dielectric	
N	COG (NPO)
B	X7R
Y	Y5V

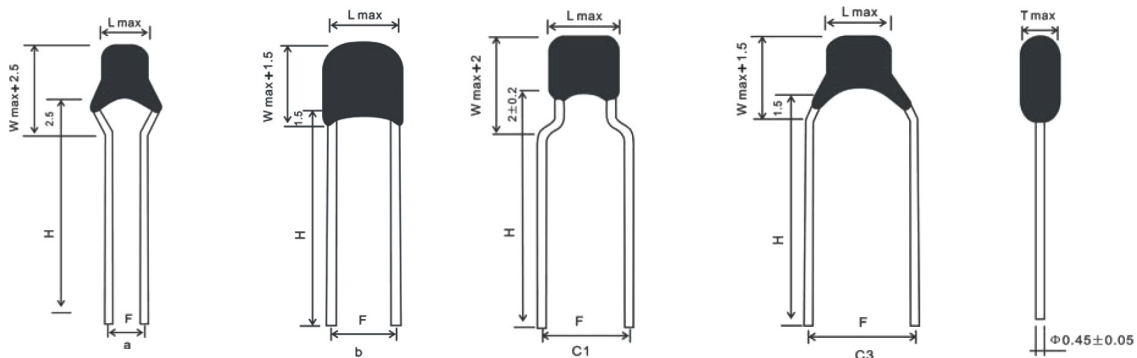
D
Capacitance
First two digits are significant third digit is number of zeros. For Example: 104=100000pF 5R6=5.6pF

E	
Tolerance	
C	±0.25pF
D	±0.5pF
J	±5%
K	±10%
M	±20%
Z	+80% -20%

F
Rated Voltage
The code meaning is same as capacitance. For Example: 101=100V 500=50V

G	
Packaging Style	
Ammo	2.54mm
	5.08mm

Dimensions:



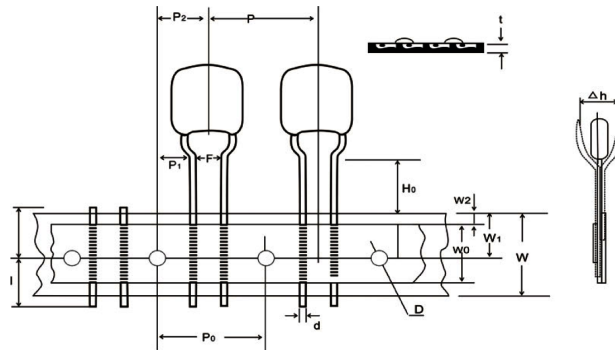
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Multilayer Ceramic Capacitor



Size Code	Shape	Dimensions (mm)					Voltage	Capacitance (pF)		
		F (±0.5)	H (±1)	L max.	W max.	T max.		NPO	X7R	Y5V
0805	a	2.54	5				25V 50V 100V	0R5~332 0R5~222 0R5~102	331~104 331~104 331~104	103~105 103~684
	b	2.54	10							
	C1	5.08	5 / 10	4.2	3.8	3.8				
	C2	5.08	5							
	C3	5.08	5 / 10							
1206	a	2.54					25V 50V 100V	0R5~682 0R5~472 0R5~392	102~224 102~104 102~105	103~125 103~105
	b	3.50	10	5	4.5	3.8				
	C1	5.08								

Packaging Style:



Description	Symbol	Dimensions (mm)	Remarks
Pitch Of Component	P	12.7 ±1.0	Cumulative Pitch Error : ±1mm /20 Pitches
Feedhold Pitch	PO	12.7 ±0.3	For F:5.08, 5.1±0.7 For F:2.54
Feed Hold Center To Lead	P1	3.85 ±0.7	
Feed Hold Centre To Component Centre	P2	8.35 ±1.3	To Lead Tip Within TOL
Lead To Lead Spacing	F	5.08 +0.8/-0.2 or 2.5 +0.8/-0.2	The alignment form the center of the lead is ±1.0mm
Component Alignment, F-R	ΔH	2 Max.	
Tape Width	W	18 ±1	
Adhesive Tape Width	W0	12 ±1	
Hole Position	W1	9 ±0.5	Adhesive Tape Must Not Protrude From Bode Paper
Adhesive Tape Position	W2	3 Max	6.5 ≤ H0-W1
Lead-Wire Clinch Height	H0	15-20 ±0.5	
Component Height	H1	32.25 Max.	
Feed Hole Diameter	D0	4 ±0.3	
Total Tape Thickness	T	0.7 ±0.2	

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